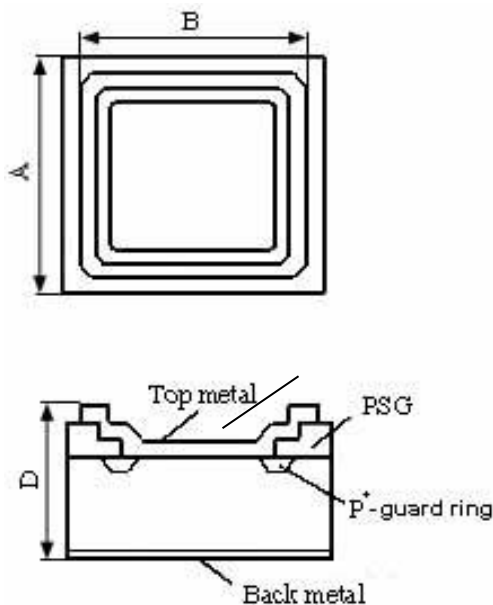




5A/60V. Die Size-65mil.

| Electrical Characteristics  | Symbol      | Unit                   | Spec. limit        | Die Sort               |
|---|-------------|------------------------|--------------------|------------------------|
| Breakdown Voltage @ $I_R=10\text{mA}$   | $V_{BR}$    | V                      | 60                 | 65                     |
| Average Rectified Forward Current   | $I_{F(AV)}$ | A                      | 5,0                | -                      |
| DC Forward Voltage @ $25^\circ\text{C}$ , $I_F=5,0\text{A}$   | $V_F$       | V                      | 0,62               | 0,6                    |
| Maximum Reverse Current<br>@ $25^\circ\text{C}$ , $V_R=65\text{V}$<br>@ $25^\circ\text{C}$ , $V_R=60\text{V}$<br>@ $125^\circ\text{C}$ , $V_R=60\text{V}$ | $I_R$       | mA                     | -<br>0,045<br>30,0 | 0,100<br>0,080<br>25,0 |
| Peak Forward Surge Current 8,3ms single half sine-wave superimposed on rated load (JEDEC METHOD)  | $I_{FSM}$   | A                      | 110                | -                      |
| Peak Repetitive Reverse Surge Current @ $2,0\mu\text{s}$ , $f=1\text{kHz}$ ., $T_J<150^\circ\text{C}$ .   | $I_{RRM}$   | A                      | 2,5                |                        |
| Electrostatic Discharge Voltage. JEDEC Method. ESD HBM. Contact.  | ESD         | kV                     | $\pm 8$ (contact)  |                        |
| Voltage Rate of Change  | $dV/dt$     | $\text{V}/\mu\text{S}$ | 10.000             |                        |
| Operating Junction Temperature  | $T_J$       | $^\circ\text{C}$       | 150                |                        |



| DIM               | ITEM                | $\mu\text{m}$ |
|-------------------|---------------------|---------------|
| $A_x$             | Wafer Form Die Size | 1650          |
| $A_y$             |                     | 1650          |
| $B_x$             | Top Metal Size      | 1510          |
| $B_y$             |                     | 1510          |
| D                 | Thickness           | 300max.       |
| Scribe line Width |                     | 80            |

Top metal:

- a) Al – for Wire Bonding;
- b) Al-Ni-Ag – for Soldering.

Backside metal: Ti-Ni-Ag.